

Description

Finalloy EBP-2010F C00 is a mineral-filled and impact-modified polypropylene-based compound.

Finalloy EBP-2010F C00 is easy to process thanks to its high MFI and good behaviour to flow lines. The typical applications are unpainted bumpers or similar parts. The high rigidity makes this material suitable for the use in thin wall parts.

Characteristics

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133-1	g/10 min	28
Mechanical properties			
Tensile modulus	ISO 527	MPa	1580
Tensile strength at yield	ISO 527	MPa	18
Elongation at break	ISO 527	%	> 60
Flexural modulus	ISO 178	MPa	1680
Charpy impact strength (notched)	ISO 179-1eA	kJ/m ²	
at 23°C			46
at -20°C			6.5
Thermal properties			
Melting range	internal method	°C	160-165
Heat Deflection Temperature	ISO 75-2	°C	
0.45 MPa - 120°C per hour			98
Linear mould shrinkage, MD, t=3mm	internal method	%	0.7 – 0,9
Coefficient of Linear Thermal Expansion	ISO 11359-2	m/m/K	75*10 ⁻⁶
Other physical properties			
Density	ISO 1183-1	g/cm ³	0.98

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery, provided storage conditions are used as given in the SDS of our product. SDS may be obtained from your technical service contact on request.

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